ABSOLUTE MAXIMUM RATINGS

(All voltages referenced to GND, unless otherwise noted.) VDD0.3V to +4V LE, SEL, IN_, X_, OUT_, D_, TX_, HPD_, RX_, AUX_ (Note 1)0.3V to + (VDD + 0.3V) IVIN VTX_I, IVIN VD_I, IVX VHPD_I, IVX VRX1_I, IVOUT VAUX_I, IVOUT VRX0_I (Note 1)0 to +2V Continuous Current (IN_ to D_/TX_, X_ to HPD_/RX1_, OUT_ to AUX_/RX0
, = = = = = = =

Peak Current (LE, SEL)	
(pulsed at 1ms, 10% duty cycle)	
Continuous Power Dissipation ($T_A = +70$ °C) for N	1ultilayer Board
56-Pin TQFN (derate 41.0mW/°C above +70°	°C)3279mV
Operating Temperature Range	40°C to +85°C
Junction Temperature	
Storage Temperature Range	-65°C to +150°C
Package Junction-to-Ambient Thermal Resistar	$nce (\theta_{JA})$
(Note 2)	24.4°C/V
Package Junction-to-Case Thermal Resistance	(θJC)
(Note 2)	
Lead Temperature (soldering)	+300°C

- Note 1: Signals on IN_, X_, OUT_, D_, TX_, HPD_, RX_, or AUX_, LE, SEL exceeding V_{DD} or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.
- **Note 2:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a 4-layer board. For detailed information on package thermal considerations, see www.maxim-ic.com/thermal-tutorial.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{DD} = +3.3V, T_A = +25^{\circ}C, \text{ unless otherwise noted.}$ (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
ANALOG SWITCH							
Analog Signal Range	IN_, X_, OUT_, D_, TX_, HPD_, RX_, AUX_		-0.1		(V _{DD} - 1.8)	V	
Voltage Between IN and D/TX, X and HPD/RX1, and OUT and AUX/RX0	IV _{IN_} - V _{TX_} I, IV _{IN_} - V _{D_} I, IV _{X_} - V _{HPD_} I, IV _{X_} - V _{RX1_} I, IV _{OUT_} - V _{AUX_} I, IV _{OUT_} - V _{RX0_} I		0		1.8	V	
On-Resistance	Ron	I _{IN} _ = I _X _ = I _{OUT} _ = 15mA, V _D _, V _{TX} _, V _{HPD} _, V _{AUX} _, or V _{RX} _ = 0V, +1.2V		8		Ω	
On-Resistance Match Between Pairs of Same Channel	ΔR _{ON}	$V_{DD} = +3.0V$, $I_{IN} = I_X = I_{OUT} = 15mA$, V_{D} , V_{TX} , V_{HPD} , V_{AUX} , or $V_{RX} = 0V$ (Notes 4, 5)		0.1	2	Ω	
On-Resistance Match Between Channels	ΔR _{ON}	$V_{DD} = +3.0V$, $I_{IN} = I_X = I_{OUT} = 15mA$, V_{D} , V_{TX} , V_{HPD} , V_{AUX} , or $V_{RX} = 0V$ (Notes 4, 5)		1.5	4	22	
On-Resistance Flatness	R _{FLAT} (ON)	V _{DD} = +3.0V, I _{IN} = I _X = I _{OUT} = 15mA, V _D , V _{TX} , V _{HPD} , V _{AUX} , or V _{RX} = 0V, +1.2V (Notes 5, 6)		0.3	1.5	Ω	

2 ______*NIXIN*

ELECTRICAL CHARACTERISTICS (continued)

(V_{DD} = +3.3V ±10%, T_A = T_{MIN} to T_{MAX} , unless otherwise noted. Typical values are at V_{DD} = +3.3V, T_A = +25°C, unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
D_ or TX_/ HPD_ or RX1_/ AUX_ or RX0_ Off-Leakage Current	ID_ (OFF) ITX_ (OFF) IHPD_ (OFF) IRX1_ (OFF) IAUX_ (OFF) IRX0_ (OFF)	V _{DD} = +3.6V , V _{IN} = V _X = V _{OUT} = 0V, +1.2V; V _D or V _{TX} , V _{HPD} or V _{RX1} , V _{AUX} or V _{RX0} = +1.2V, 0V	-1		+1	μА
IN_/X_/OUT_ On-Leakage Current	IIN_(ON) IX_(ON) IOUT_(ON)	V _{DD} = +3.6V , V _{IN} = V _X = V _{OUT} = 0V, +1.2V; V _D or V _{TX} = V _{IN} or unconnected, V _{HPD} or V _{RX1} = V _X or unconnected, V _{AUX} or V _{RX0} = V _{OUT} or unconnected	-1		+1	
DIGITAL SIGNALS						
SEL to Switch Turn-On Time	tON_SEL	$\begin{split} &V_{D_} \text{ or } V_{TX_} = +1.0 V, \ R_L = 50 \Omega, \\ &V_{HPD_} \text{ or } V_{RX1_} = +1.0 V, \ R_L = 50 \Omega, \\ &V_{AUX_} \text{ or } V_{RX0_} = +1.0 V, \ R_L = 50 \Omega, \\ &LE = V_{DD}, \ C_L = 100 \text{pf (Figure 1)} \end{split}$		55	120	ns
SEL to Switch Turn-Off Time	toff_sel	$\begin{split} &V_{D_} \text{ or } V_{TX_} = +1.0 \text{V}, \ R_L = 50 \Omega, \\ &V_{HPD_} \text{ or } V_{RX1_} = +1.0 \text{V}, \ R_L = 50 \Omega, \\ &V_{AUX_} \text{ or } V_{RX0_} = +1.0 \text{V}, \ R_L = 50 \Omega, \\ &LE = V_{DD}, \ C_L = 100 \text{pf (Figure 1)} \end{split}$		8	50	ns
LE Setup Time SEL to LE	tsu	$\begin{array}{l} V_{D_} \text{ or } V_{TX_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{HPD_} \text{ or } V_{RX1_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{AUX_} \text{ or } V_{RX0_} = +1.0 \text{V, } R_L = 50 \Omega \\ \text{(Figure 1)} \end{array}$		2		ns
LE Hold Time SEL to LE	tHOLD	$\begin{array}{l} V_{D_} \text{ or } V_{TX_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{HPD_} \text{ or } V_{RX1_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{AUX_} \text{ or } V_{RX0_} = +1.0 \text{V, } R_L = 50 \Omega, \\ \text{(Figure 1)} \end{array}$		2		ns
LE Minimum Pulse-Width Low	t₩	$\begin{array}{l} V_{D_} \text{ or } V_{TX_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{HPD_} \text{ or } V_{RX1_} = +1.0 \text{V, } R_L = 50 \Omega, \\ V_{AUX_} \text{ or } V_{RX0_} = +1.0 \text{V, } R_L = 50 \Omega \\ \text{(Figure 1)} \end{array}$	40			ns
Differential leadation		f = 2.5GHz		-1.5		
Differential Insertion Loss (Figure 2)	S _{DD21}	f = 5.0GHz		-3.3		dB
· · · · · · · · · · · · · · · · · · ·		f = 7.5GHz		-4.9		
Differential Crosstalk (Figure 2)		f = 2.5GHz		-40		
	SDDCTK	f = 5.0GHz		-23		dB
D:#	0	f = 7.5GHz		-28		-10
Differential Off-Isolation	S _{DD21_OFF}	f = 3.0GHz		-22		dB
Differential Return Loss (Figure 2)	95511	f = 2.8GHz		-21		dB
Dinerential neturn Loss (Figure 2)	S _{DD11}	f = 5.0GHz		-8		UD
		f = 7.5GHz		-7		



ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{DD} = +3.3V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Signal Data Rate	BR	$R_S = R_L = 100\Omega$ balanced		10		Gbps
Differential -3dB Bandwidth	DBW	$R_S = R_L = 100\Omega$ balanced		5		GHz
LOGIC INPUT (LE, SEL)						
Input Logic-High	VIH		1.4			V
Input Logic-Low	VIL				0.5	V
Input Logic Hysteresis	V _{HYST}			100		mV
Input Leakage Current	I _{IN}	V _{IN} = 0 or V _{DD}	-1		+1	μΑ
POWER SUPPLY						
Power Supply Range	V _{DD}		3.0		3.6	V
V _{DD} Supply Current	I _{DD}	$V_{IN} = 0$ or V_{DD}			850	μΑ

Note 3: All units are 100% production tested at $T_A = +85^{\circ}C$. Limits over the operating temperature range are guaranteed by design and characterization and are not production tested.

Note 4: $\Delta R_{ON} = R_{ON} (MAX) - R_{ON} (MIN)$.

Note 5: Guaranteed by design. Not production tested.

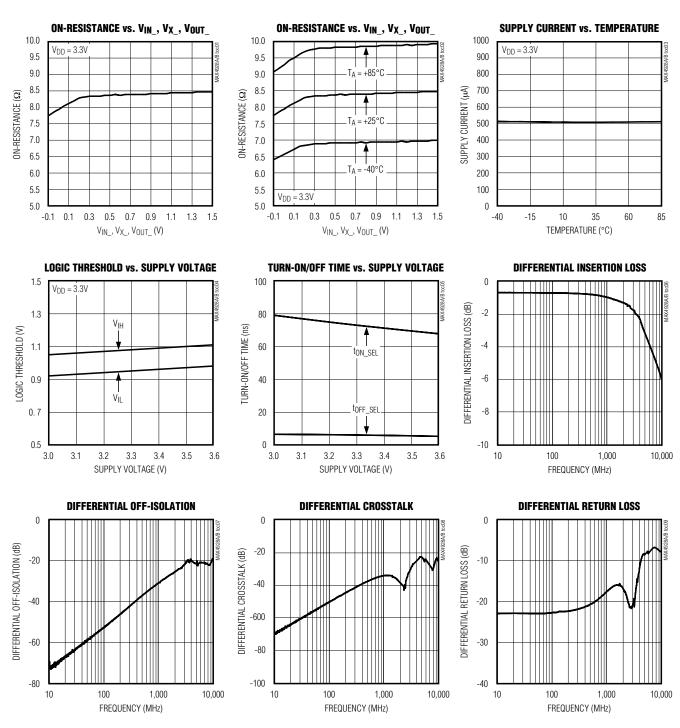
Note 6: Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal range.

5

DisplayPort/PCIe Passive Switches

Typical Operating Characteristics

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$



Downloaded from Arrow.com.

MIXIM

Test Circuits/Timing Diagrams

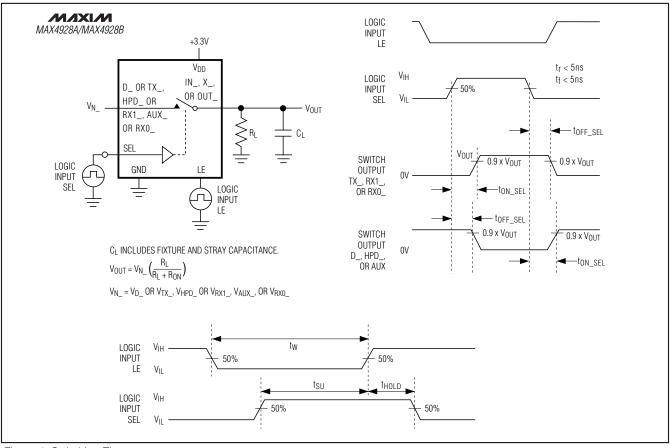


Figure 1. Switching Time

· _____ //IXI/N

Test Circuits/Timing Diagrams (continued)

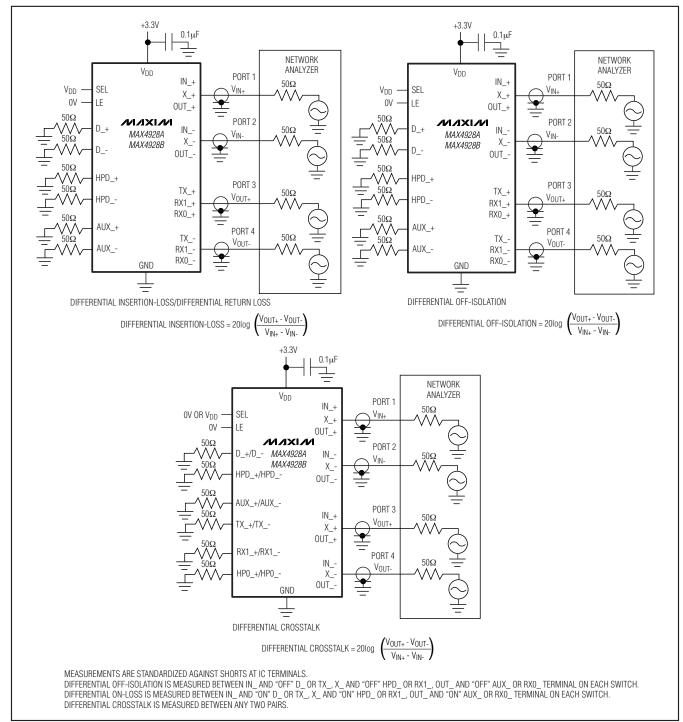


Figure 2. Differential On-Loss, Differential Off-Isolation, and Differential Crosstalk

Pin Description

PIN						
MAX4928A	MAX4928B	NAME	FUNCTION			
1, 11, 16, 20, 21, 28, 29, 35, 48, 49, 56	1, 11, 16, 20, 21, 28, 29, 35, 48, 49, 56	GND	Ground			
2	4	IN0+	Analog Switch 1—Common Positive Terminal			
3	5	INO-	Analog Switch 1—Common Negative Terminal			
4	7	IN1+	Analog Switch 2—Common Positive Terminal			
5	8	IN1-	Analog Switch 2—Common Negative Terminal			
6, 17, 22, 27, 34, 50, 55	6, 17, 22, 27, 34, 50, 55	V_{DD}	Positive Supply Voltage Input. Connect V_{DD} to a +3.0V to +3.6V supply voltage. Bypass V_{DD} to GND with a 0.1 μ F ceramic capacitor placed as close as possible to the device. See the <i>Board Layout</i> section.			
7	9	IN2+	Analog Switch 3—Common Positive Terminal			
8	10	IN2-	Analog Switch 3—Common Negative Terminal			
9	12	IN3+	Analog Switch 4—Common Positive Terminal			
10	13	IN3-	Analog Switch 4—Common Negative Terminal			
12	14	OUT+	Analog Switch 5—Common Positive Terminal			
13	15	OUT-	Analog Switch 5—Common Negative Terminal			
14	18	X+	Analog Switch 6—Common Positive Terminal			
15	19	X-	Analog Switch 6—Common Negative Terminal			
18	2	SEL	Control Signal Input			
19	3	LE	Latch Enable Input			
23	30	HPD2	Analog Switch 6—Normally Open Negative Terminal			
24	31	HPD1	Analog Switch 6—Normally Open Positive Terminal			
25	32	AUX-	Analog Switch 5—Normally Open Negative Terminal			
26	33	AUX+	Analog Switch 5—Normally Open Positive Terminal			
30	23	RX1-	Analog Switch 6—Normally Closed Negative Terminal			
31	24	RX1+	Analog Switch 6—Normally Closed Positive Terminal			
32	25	RX0-	Analog Switch 5—Normally Closed Negative Terminal			
33	26	RX0+	Analog Switch 5—Normally Closed Positive Terminal			
36	44	D3-	Analog Switch 4—Normally Open Negative Terminal			
37	45	D3+	Analog Switch 4—Normally Open Positive Terminal			
38	46	D2-	Analog Switch 3—Normally Open Negative Terminal			
39	47	D2+	Analog Switch 3—Normally Open Positive Terminal			
40	51	D1-	Analog Switch 2—Normally Open Negative Terminal			
41	52	D1+	Analog Switch 2—Normally Open Positive Terminal			
42	53	D0-	Analog Switch 1—Normally Open Negative Terminal			
43	54	D0+	Analog Switch 1—Normally Open Positive Terminal			
44	36	TX3-	Analog Switch 4—Normally Closed Negative Terminal			
45	37	TX3+	Analog Switch 4—Normally Closed Positive Terminal			
46	38	TX2-	Analog Switch 3—Normally Closed Negative Terminal			

Pin Description (continued)

Р	IN	NAME	FUNCTION	
MAX4928A	MAX4928B	NAIVIE		
47	39	TX2+	Analog Switch 3—Normally Closed Positive Terminal	
51	40	TX1-	Analog Switch 2—Normally Closed Negative Terminal	
52	41	TX1+	Analog Switch 2—Normally Closed Positive Terminal	
53	42	TX0-	Analog Switch 1—Normally Closed Negative Terminal	
54	43	TX0+	Analog Switch 1—Normally Closed Positive Terminal	
_	_	EP	Exposed Pad. Connect EP to GND. Exposed pad internally connected to GND.	

Detailed Description

The MAX4928A/MAX4928B high-speed passive switches route PCI Express (PCIe) data and/or DisplayPort signals between two possible destinations. The MAX4928A/MAX4928B are ideal for routing signals between a graphics memory controller hub (GMCH) and either a DisplayPort or PCIe connector.

The MAX4928A/MAX4928B feature a single digital control input (SEL) to switch signal paths and a latch input (LE) that holds the switches in a given state.

Digital Control Input (SEL)

The MAX4928A/MAX4928B provide a single digital control input (SEL) to select the signal path between the IN_ and D_/TX_, X_ and HPD_/RX1_, and OUT_ and AUX_/RX0_ channels. The truth tables for the MAX4928A/MAX4928B are depicted in the *Functional Diagrams/Truth Table*. Drive SEL rail-to-rail to minimize power consumption.

Latch Control Input (LE)

The MAX4928A/MAX4928B provide a single digital control input (LE) to latch the signal paths between the IN_ and D_/TX_, X_ and HPD_/RX1_, and OUT_ and AUX_/RX0_ channels. When LE is driven high, the switches are held in their previous state, regardless of the input signal to SEL. Drive LE rail-to-rail to minimize power consumption.

Analog Signal Levels

The MAX4928A/MAX4928B accept standard PCIe signals to a maximum of (V_{DD} - 1.8V). Signals on the IN_+ channels are routed to either the D_+ or TX_+ channels, signals on the X+ channel are routed to either HPD1 or RX1+ channels, and signals on the OUT+ channel are routed to either AUX+ or RX0+ channels. Signals on the

IN_- channels are routed to either the D_- or TX_- channels, signals on the X- channel are routed to either HPD2 or RX1- channels, and signals on the OUT- channel are routed to either AUX- or RX0- channels. The MAX4928A/MAX4928B are bidirectional switches, allowing IN_, X_, OUT_, D_, TX_, HPD_, RX_, and AUX_ to be used as either inputs or outputs.

Applications Information

DisplayPort/PCIe Switching

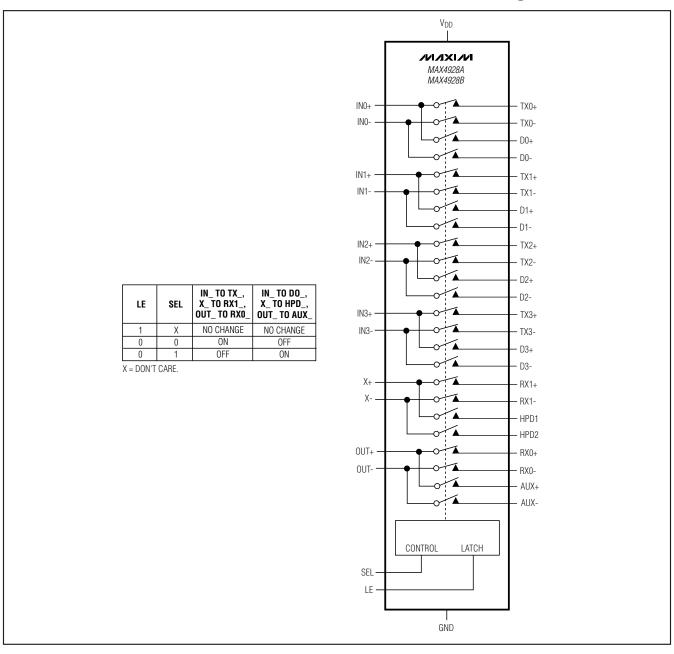
The MAX4928A/MAX4928B primary applications are aimed to switch between a GMCH and either a DisplayPort or PCIe connector. The MAX4928A/MAX4928B contain n-channel switches to permit differential signals to be selected between a PCIe Gen II socket or to a DisplayPort connector. Each device handles up to six pairs of signals. The DisplayPort signal is an AC-coupled 8b/10b encoded differential signal ranging up to 2.7 Gbps. The PCIe Gen I and Gen II signals are AC-coupled, 8b/10b encoded differential signals ranging up to 5.0Gbps.

Board Layout

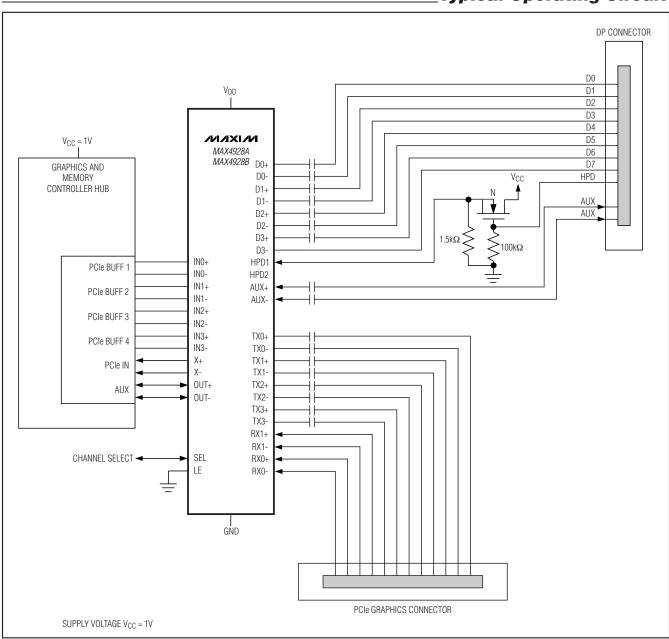
High-speed switches require proper layout and design procedures for optimum performance. Keep design-controlled impedance PCB traces as short as possible or follow impedance layouts per the PCle specification. Ensure that power-supply bypass capacitors are placed as close as possible to the device. Multiple bypass capacitors are recommended. Connect all grounds and the exposed pad to large ground planes.

PROCESS: CMOS

Functional Diagram/Truth Table



_Typical Operating Circuit



Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
56 TQFN-EP	T56511-1	<u>21-0187</u>

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	2/08	Initial release	_
1	8/08	Changed functional diagram and limits	1, 2, 11

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600 _

_ 13